BLF640

Broadband power LDMOS transistor

Rev. 2 — 11 April 2013

Product data sheet

1. Product profile

1.1 General description

10 W LDMOS power transistor for applications at frequencies from HF to 2200 MHz

Table 1. Typical performance

 I_{Dq} = 100 mA; T_{case} = 25 °C in a common source class-AB production test circuit.

Test signal	f	V_{DS}	$P_{L(AV)}$	G _p	η_{D}	ACPR
	(MHz)	(V)	(W)	(dB)	(%)	(dBc)
2-carrier W-CDMA	2110 to 2170	28	0.7	18.5	15	-50 <u>[1]</u>
1-carrier W-CDMA	2110 to 2170	28	2	19.3	31	_39 <u>[1]</u>

^[1] Test signal: 3GPP; test model 1; 64 DPCH; PAR = 7.5 dB at 0.01 % probability on CCDF per carrier; carrier spacing 5 MHz.

1.2 Features and benefits

- Easy power control
- Integrated ESD protection
- Excellent ruggedness
- High efficiency
- Excellent thermal stability
- No internal matching for broadband operation
- Compliant to Directive 2002/95/EC, regarding Restriction of Hazardous Substances (RoHS)

1.3 Applications

- RF power amplifiers for applications in the HF to 2200 MHz frequency range
- Broadcast drivers



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2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Graphic symbol
1	drain		,
2	gate		1
3	source		2 — 3 sym112

^[1] Connected to flange.

3. Ordering information

Table 3. Ordering information

Type number	Package	9	
	Name	Description	Version
BLF640	-	ceramic surface-mounted package; 2 leads	SOT538A

4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	drain-source voltage		-	65	V
V_{GS}	gate-source voltage		-0.5	+13	V
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		-	225	°C

5. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Тур	Unit
R _{th(j-case)}	thermal resistance from junction to case	T_{case} = 80 °C; $P_{L(AV)}$ = 11 W	<u>[1]</u> 3.2	K/W

^[1] Thermal resistance is determined under specified RF operating conditions

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6. Characteristics

Table 6. DC characteristics

 $T_i = 25$ °C unless otherwise specified

,	-					
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$V_{(BR)DSS}$	drain-source breakdown voltage	$V_{GS} = 0 \text{ V}; I_D = 0.5 \text{ mA}$	65	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	$V_{DS} = 10 \text{ V}; I_D = 18 \text{ mA}$	1.4	1.9	2.4	V
I _{DSS}	drain leakage current	$V_{GS} = 0 \text{ V}; V_{DS} = 28 \text{ V}$	-	-	1.5	μΑ
I _{DSX}	drain cut-off current	$V_{GS} = V_{GS(th)} + 3.75 \text{ V};$ $V_{DS} = 10 \text{ V}$	-	3.1	-	Α
I_{GSS}	gate leakage current	$V_{GS} = 11 \text{ V}; V_{DS} = 0 \text{ V}$	-	-	150	nA
9 _{fs}	forward transconductance	$V_{DS} = 10 \text{ V}; I_{D} = 0.9 \text{ A}$	-	0.5	-	S
R _{DS(on)}	drain-source on-state resistance	$V_{GS} = V_{GS(th)} + 3.75 \text{ V};$ $I_D = 0.625 \text{ A}$	-	0.4	-	Ω

Table 7. AC characteristics

 $T_i = 25$ °C unless otherwise specified

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
C_{rs}	feedback capacitance	$V_{GS} = 0 \text{ V}; V_{DS} = 28 \text{ V};$ f = 1 MHz	-	0.5	-	pF

Table 8. RF characteristics

PAR 7.5 dB at 0.01 % probability on CCDF; 3GPP test model 1; 1-64 PDPCH; RF performance at V_{DS} = 28 V; I_{Dq} = 100 mA; T_{case} = 25 °C; unless otherwise specified; in a class-AB production test circuit.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Test signa	al: 2-carrier W-CDMA	$f_1 = 2112.5 \text{ MHz}; f_2 = 2117.5 \text{ MHz}; f_3 = 2$	162.5 MHz	; f ₄ = 2	167.5 N	ИHz
Gp	power gain	$P_{L(AV)} = 0.7 W$	-	18.5	-	dB
η_{D}	drain efficiency	$P_{L(AV)} = 0.7 W$	-	15	-	%
ACPR	adjacent channel power ratio	$P_{L(AV)} = 0.7 W$	-	-50	-	dBc
Test signa	al: 1-carrier W-CDMA	$f_1 = 2112.5 \text{ MHz}; f_2 = 2167.5 \text{ MHz}$				
Gp	power gain	$P_{L(AV)} = 2 W$	17.3	19.3	-	dB
η_{D}	drain efficiency	$P_{L(AV)} = 2 W$	29	31	-	%
ACPR	adjacent channel power ratio	$P_{L(AV)} = 2 W$	-	-39	-36	dBc

7. Test information

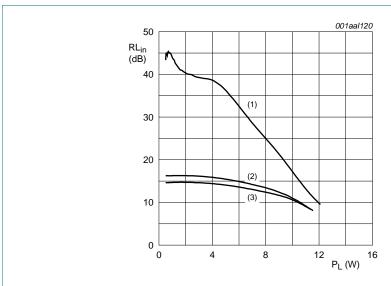
7.1 Ruggedness in class-AB operation

The BLF640 is capable of withstanding a load mismatch corresponding to VSWR = 10 : 1 through all phases under the following conditions: V_{DS} = 28 V; f = 2140 MHz at P_{L} = 10 W.

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7.2 Graphical data

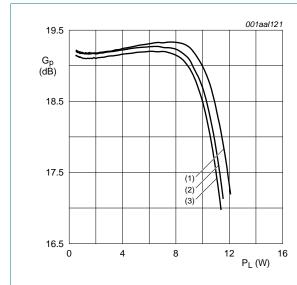
7.2.1 CW



 $V_{DS} = 28 \text{ V}; I_{Dq} = 100 \text{ mA}.$

- (1) f = 2.11 GHz
- (2) f = 2.14 GHz
- (3) f = 2.17 GHz

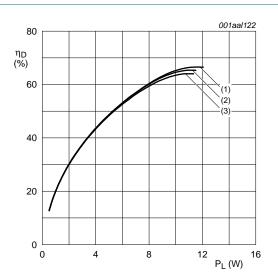
Fig 1. Input return loss as a function of load power; typical values



 $V_{DS} = 28 \text{ V}; I_{Dq} = 100 \text{ mA}.$

- (1) f = 2.11 GHz
- (2) f = 2.14 GHz
- (3) f = 2.17 GHz

Fig 2. Power gain as a function of load power; typical values



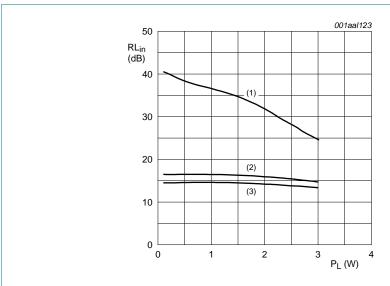
 $V_{DS} = 28 \text{ V}; I_{Dq} = 100 \text{ mA}.$

- (1) f = 2.11 GHz
- (2) f = 2.14 GHz
- (3) f = 2.17 GHz

Fig 3. Drain efficiency as a function of load power; typical values

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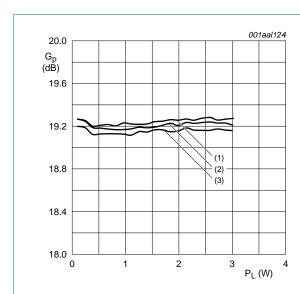
7.2.2 1-Carrier W-CDMA



 $V_{DS} = 28 \text{ V}; I_{Dq} = 100 \text{ mA}.$

- (1) f = 2.11 GHz
- (2) f = 2.14 GHz
- (3) f = 2.17 GHz

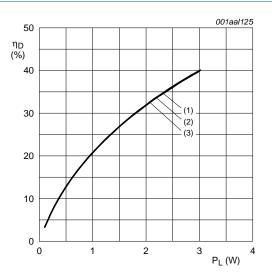
Fig 4. Input return loss as a function of load power; typical values



 $V_{DS} = 28 \text{ V}; I_{Dq} = 100 \text{ mA}.$

- (1) f = 2.11 GHz
- (2) f = 2.14 GHz
- (3) f = 2.17 GHz

Fig 5. Power gain as a function of load power; typical values

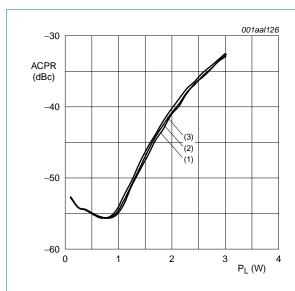


 $V_{DS} = 28 \text{ V}; I_{Dq} = 100 \text{ mA}.$

- (1) f = 2.11 GHz
- (2) f = 2.14 GHz
- (3) f = 2.17 GHz

Fig 6. Drain efficiency as a function of load power; typical values

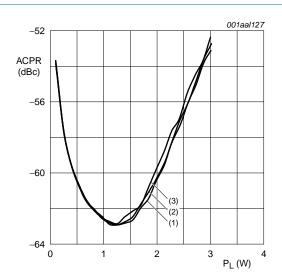
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 $V_{DS} = 28 \text{ V}$; $I_{Dq} = 100 \text{ mA}$; carrier spacing 5 MHz.

- (1) f = 2.11 GHz
- (2) f = 2.14 GHz
- (3) f = 2.17 GHz

Fig 7. Adjacent channel power ratio as a function of load power; typical values

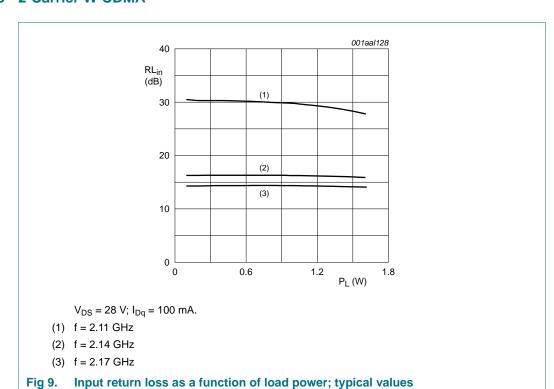


 V_{DS} = 28 V; I_{Dq} = 100 mA; carrier spacing 10 MHz.

- (1) f = 2.11 GHz
- (2) f = 2.14 GHz
- (3) f = 2.17 GHz

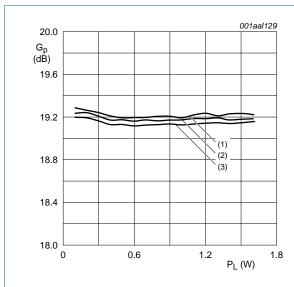
Fig 8. Adjacent channel power ratio as a function of load power; typical values

7.2.3 2-Carrier W-CDMA



BLF640

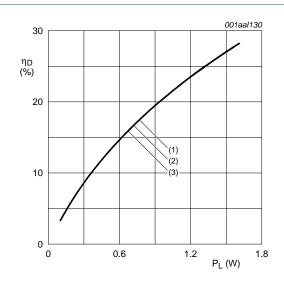
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 $V_{DS} = 28 \text{ V}; I_{Dq} = 100 \text{ mA}.$

- (1) f = 2.11 GHz
- (2) f = 2.14 GHz
- (3) f = 2.17 GHz

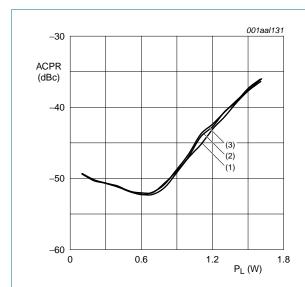
Fig 10. Power gain as a function of load power; typical values



 $V_{DS} = 28 \text{ V}; I_{Dq} = 100 \text{ mA}.$

- (1) f = 2.11 GHz
- (2) f = 2.14 GHz
- (3) f = 2.17 GHz

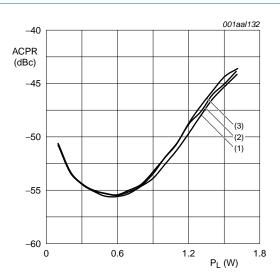
Fig 11. Drain efficiency as a function of load power; typical values



 V_{DS} = 28 V; I_{Dq} = 100 mA; carrier spacing 5 MHz.

- (1) f = 2.11 GHz
- (2) f = 2.14 GHz
- (3) f = 2.17 GHz

Fig 12. Adjacent channel power ratio as a function of load power; typical values



 V_{DS} = 28 V; I_{Dq} = 100 mA; carrier spacing 10 MHz.

- (1) f = 2.11 GHz
- (2) f = 2.14 GHz
- (3) f = 2.17 GHz

Fig 13. Adjacent channel power ratio as a function of load power; typical values

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8. Package outline

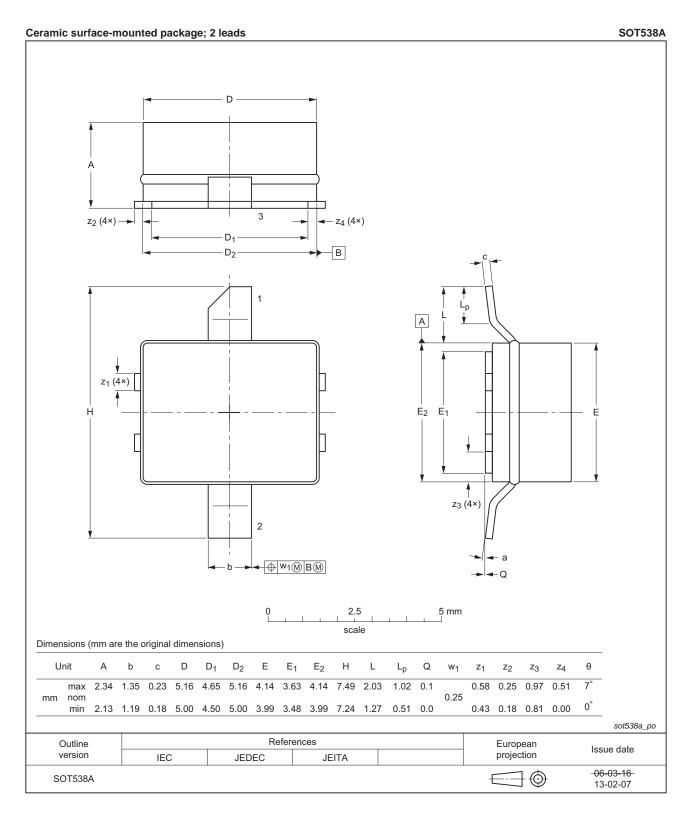


Fig 14. Package outline SOT538A

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9. Handling information

CAUTION



This device is sensitive to ElectroStatic Discharge (ESD). Observe precautions for handling electrostatic sensitive devices.

Such precautions are described in the ANSI/ESD S20.20, IEC/ST 61340-5, JESD625-A or equivalent standards.

10. Abbreviations

Table 9. Abbreviations

14515 61 71551	
Acronym	Description
3GPP	3rd Generation Partnership Project
CCDF	Complementary Cumulative Distribution Function
CW	Continuous Wave
DPCH	Dedicated Physical CHannel
ESD	ElectroStatic Discharge
HF	High Frequency
LDMOS	Laterally Diffused Metal Oxide Semiconductor
PAR	Peak-to-Average Ratio
PDPCH	transmission Power of the Dedicated Physical CHannel
PHS	Personal Handy-phone System
VSWR	Voltage Standing Wave Ratio
W-CDMA	Wideband Code Division Multiple Access

11. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes	
BLF640 v.2	20130411	Product data sheet	-	BLF640 v.1	
Modifications:	 Package outline drawings have been updated to the latest version. 				
BLF640 v.1	20121207	Product data sheet	-	-	

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12. Legal information

12.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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